

# SOT1074-1

plastic thermal enhanced very very thin quad flat package;  
no leads; 48 terminals; body 7 x 7 x 0.65 mm

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	Q (quad)
<b>Package type descriptive code</b>	HWQFN48
<b>Package type industry code</b>	HWQFN48
<b>Package style descriptive code</b>	HWQFN (thermal enhanced very very thin quad flatpack; no leads)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	P (plastic)
<b>IEC package outline code</b>	---
<b>JEDEC package outline code</b>	---
<b>JEITA package outline code</b>	---
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	14-3-2008

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	6.9	-	7	7.1	mm
E	package width	6.9	-	7	7.1	mm
A	seated height	0.6	-	0.65	0.8	mm
A <sub>2</sub>	package height	[tbd]	-	0.65	[tbd]	mm
n <sub>2</sub>	actual quantity of termination	-	-	48	-	

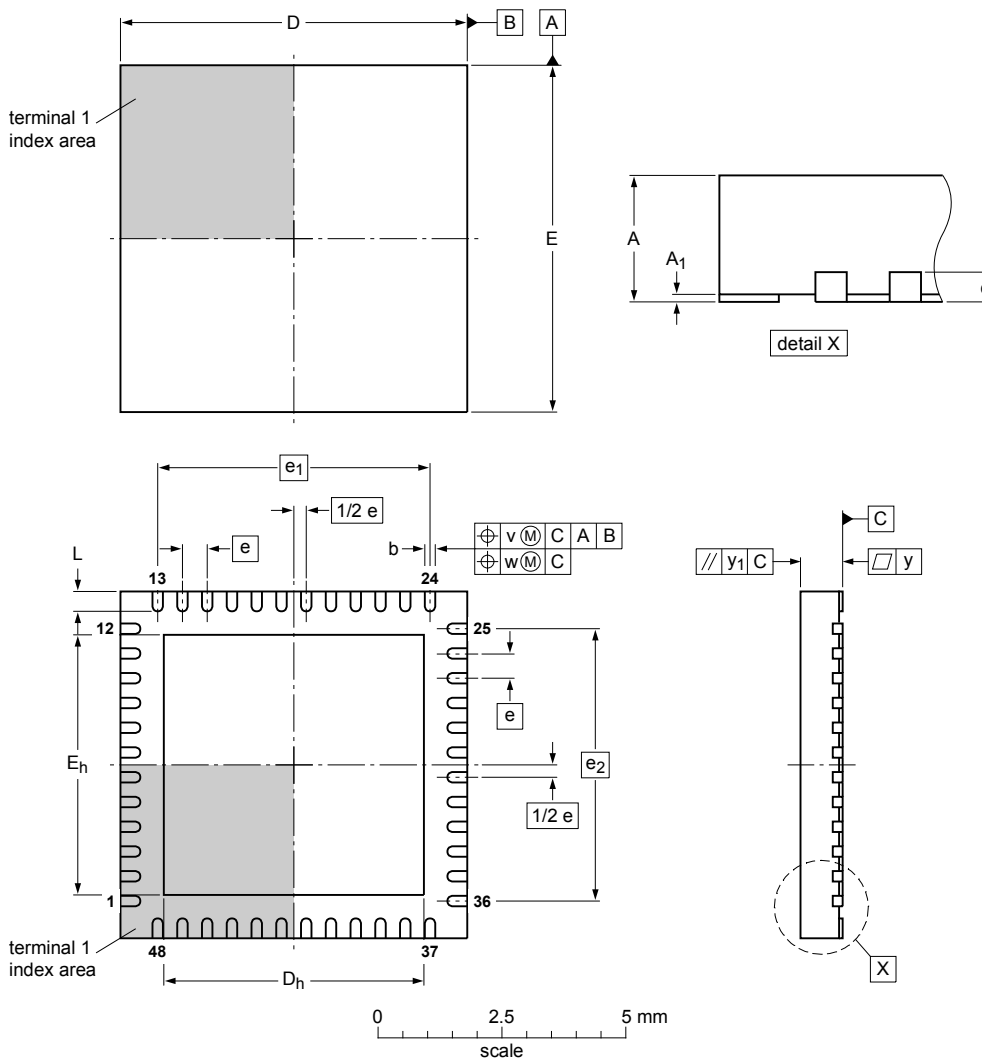


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## 2. Package outline

HWQFN48: plastic thermal enhanced very very thin quad flat package; no leads; 48 terminals; body 7 x 7 x 0.65 mm

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DIMENSIONS (mm are the original dimensions)

UNIT		A <sup>(1)</sup>	A <sub>1</sub>	b	c	D <sup>(1)</sup>	D <sub>h</sub>	E <sup>(1)</sup>	E <sub>h</sub>	e	e <sub>1</sub>	e <sub>2</sub>	L	v	w	y	y <sub>1</sub>
mm	max	0.80	0.05	0.30	0.2	7.1	5.40	7.1	5.40	0.5	5.5	5.5	0.5	0.1	0.05	0.05	0.1
	nom	0.65	0.02	0.21	0.2	7.0	5.25	7.0	5.25	0.5	5.5	5.5	0.4	0.1	0.05	0.05	0.1
	min	0.60	0.00	0.18	0.2	6.9	5.10	6.9	5.10	0.5	5.5	5.5	0.3	0.1	0.05	0.05	0.1

Note

1. Plastic or metal protrusions of 0.075 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT1074-1	---	---	---			08-03-06 08-03-14

Fig. 1. Package outline HWQFN48 (SOT1074-1)

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### 3. Legal information

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